



DEFENSE LOGISTICS AGENCY
 DEFENSE SUPPLY CENTER, COLUMBUS
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 COLUMBUS, OH 43218-3990

IN REPLY
REFER TO

DSCC-VQ (VQE-09-017372/Mr. Ciesla/614-692-0624/jpc)

February 6, 2009

SUBJECT: Notification of Qualification, MIL-PRF-31032, CAGE Code 21971, FSC 5998

Mr. Tom Scholl
 Philway Products, Inc.
 701 Virginia Avenue
 Ashland, OH 44806

Dear Mr. Scholl:

Qualification of your products is granted under the current issue of the specification as a result of successful qualification testing to Department of Defense Performance Specification MIL-PRF-31032, Printed Circuit Board/Printed Wiring Board, and associated specification MIL-PRF-31032 /1 & /2. The material and classification indicated below shall be listed on Qualified Manufacturers List QML-31032.

Changes to your current qualification listing are listed in bold and italics below:

MIL-PRF31032/1 & <i>MIL-PRF31032/2</i>	QUALIFICATION LETTERS:
Maximum Panel Size <i>18" X 24"</i>	VQ-09-017325 (add-on)
Maximum Board Thickness 0.09"	VQ-99-001107 (initial)
Maximum Base CU Thickness <i>0.0028"</i>	
Max/Min Through Hole Size <i>0.250" / 0.008"</i>	
Aspect Ratio <i>8:1</i>	
Maximum Number of Layers 12	
Minimum Conductor Width 0.005"	
Minimum Conductor Spacing 0.005"	
Part Mounting THM, SMT, MIX	
	GF: Woven E-glass, Epoxy Resin, Flame Resistant
Rigid Base Materials	GI: Glass Base, Woven, Polyimide Resin, Heat Resistant
	GM: Glass Base, Woven, Triazine and/or Bismaleimide Modified Epoxy Resin, Flame Resistant
Finish Systems	HASL, <i>ENIG</i>
Hole Preparation	Permanganate Desmear/Etchback
Alternate Construction	<i>Foil Lamination</i>
Copper Plating	Electrodeposited Acid Copper.
Solder Resist	Liquid Photo-imageable (LPI)
Controlled Impedance	Microstrip, Single Line, Single Ended, and Differential methods, ±5% at 50-Ω
Through Hole Metallization	<i>Electroless Copper</i>

